CLAIMS

1. A substrate for a semiconductor device, on which a circuit component can be mounted, characterized in,

that a surface opposite to an element mounting surface is counterbored so as to form a component mounting hole where a connection terminal, which will be electrically connected to the circuit component, is exposed in the inner bottom face.

2. The substrate according to claim 1, wherein the component mounting hole is located in a semiconductor element mounting area.

3. The substrate according to claim 2, wherein the circuit component, which is electrically connected to the connection terminal, is mounted in the component mounting hole.

4. A semiconductor device comprising: the substrate of claim 3; and a semiconductor element being mounted on the substrate by flip-chip connection.

5. The substrate according to claim 1, wherein the substrate is constituted by a core plate and a cable layer or layers formed on the core plate, and

the surface of the substrate, which is opposite to the element mounting surface thereof, is counterbored so as to form a component mounting hole where a connection terminal, which is formed in the cable layer, is exposed in the inner bottom face.

6. The substrate according to claim 5, wherein the component mounting hole is located in a semiconductor element mounting area.

7. The substrate according to claim 6, wherein the circuit component, which is electrically connected to the connection terminal, is mounted in the component mounting hole.

8. The substrate according to claim 7, wherein a decoupling capacitor

is mounted as the circuit component.

9. A semiconductor device comprising: the substrate of claim 7 or 8; and a semiconductor element being mounted on the substrate by flip-chip connection.